

10/079/14

Abstract of the Disclosure:

An electronic component includes a semiconductor chip which has an active upper side and a passive rear side. The semiconductor chip is surrounded by a sawn edge. This edge of 5 semiconductor material has profile-sawn contours. The profile-sawn contours are surrounded by a plastics composition forming an edge of plastic. The plastics composition is in form-locking engagement with the profile-sawn contours. A method of producing a component of this type is also provided.

2007914-1022002

MB/tk